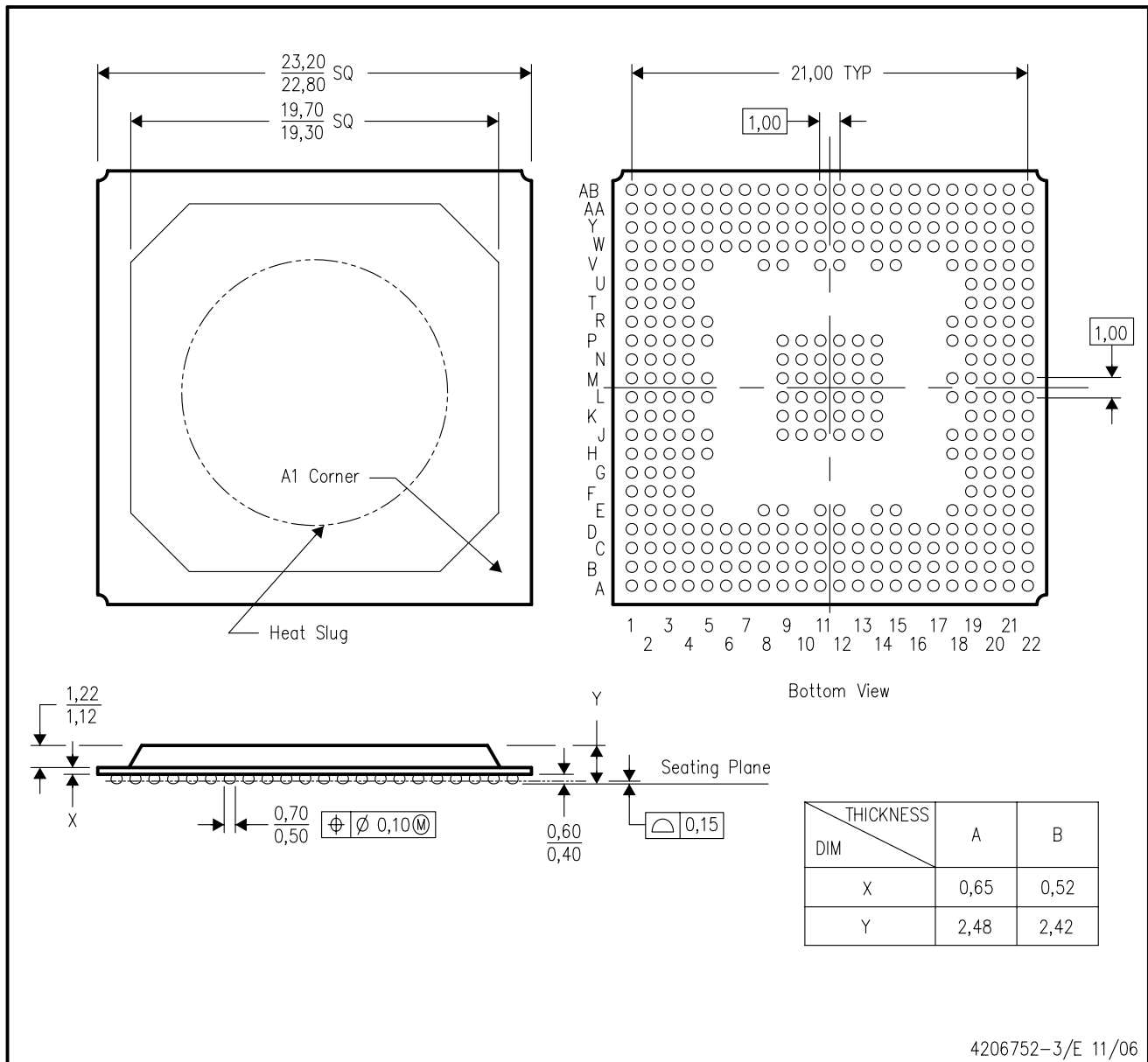


ZDU (S-PBGA-N352)

PLASTIC BALL GRID ARRAY



4206752-3/E 11/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-151
 - D. Thermally enhanced molded plastic package with heat slug (HSL).
 - E. This is a lead-free solder ball design.

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